imall

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

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1700 V

250 mΩ

2.0 V

8 A

 V_{DS}

ID

V_{DS(ON)}

R_{DS(ON)}

Normally – OFF Silicon Carbide Super Junction Transistor

Features

- 175 °C maximum operating temperature
- Temperature independent switching performance
- Gate oxide free SiC switch
- Suitable for connecting an anti-parallel diode
- · Positive temperature coefficient for easy paralleling
- Low gate charge
- · Low intrinsic capacitance

Package

RoHS Compliant





TO-247AB

Advantages

- Low switching losses
- Higher efficiency
- High temperature operation
- · High short circuit withstand capability

Applications

- Down Hole Oil Drilling, Geothermal Instrumentation
- Hybrid Electric Vehicles (HEV)
- Solar Inverters
- Switched-Mode Power Supply (SMPS)
- Power Factor Correction (PFC)
- Induction Heating
- Uninterruptible Power Supply (UPS)
- Motor Drives

Maximum Ratings unless otherwise specified

Parameter	Symbol	Conditions	Values	Unit
Drain – Source Voltage	V _{DS}	$V_{GS} = 0 V$	1700	V
Continuous Drain Current	ID	T _{C,MAX} = 90 °C	8	А
Gate Peak Current	I _{GM}		5	А
Reverse Gate – Source Voltage	V _{SG}		60	V
Reverse Drain – Source Voltage	V _{SD}		50	V
Power Dissipation	P _{tot}	T _C = 25 °C	16	W
Storage Temperature	T _{stg}		-55 to 175	°C

Electrical Characteristics at T_i = 175 °C, unless otherwise specified

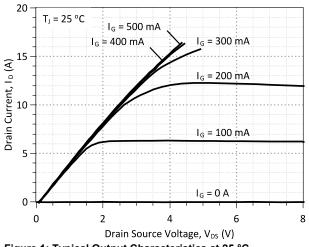
Beremeter	Symphol	Conditions -	Values		11	
Parameter	Symbol	Conditions	min.	typ.	max.	Unit
On Characteristics						
		I _D = 8 A, I _G = 500 mA, T _j = 25 °C		2.0		
Drain – Source On Voltage	V _{DS(ON)}	I _D = 8 A, I _G = 1000 mA, T _j = 125 °C		3.3		V
-		I _D = 8 A, I _G = 1000 mA, T _j = 175 °C		4.5		
		I _D = 8 A, I _G = 500 mA, T _j = 25 °C		250		
Drain – Source On Resistance	R _{DS(ON)}	I _D = 8 A, I _G = 1000 mA, T _j = 125 °C		400		mΩ
		I _D = 8 A, I _G = 1000 mA, T _j = 175 °C		550		
	$V_{GS(FWD)}$	I _G = 500 mA, T _j = 25 °C		3.0		V
Gate Forward Voltage		I _G = 500 mA, T _j = 175 °C		2.8		v
DC Current Gain	P	V _{DS} = 5 V, I _D = 8 A, T _i = 25 °C		65		
	β	V _{DS} = 5 V, I _D = 8 A, T _j = 175 °C		40		
Off Characteristics						
		V _R = 1700 V, V _{GS} = 0 V, T _i = 25 °C		0.1		
Drain Leakage Current	IDSS	V _R = 1700 V, V _{GS} = 0 V, T _j = 125 °C		0.5		μA
		V _R = 1700 V, V _{GS} = 0 V, T _i = 175 °C		2.0		



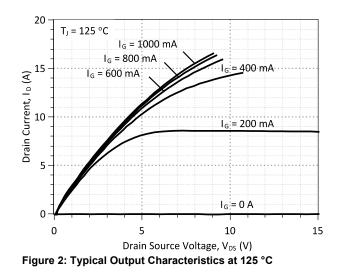
Electrical Characteristics at T_j = 175 °C, unless otherwise specified

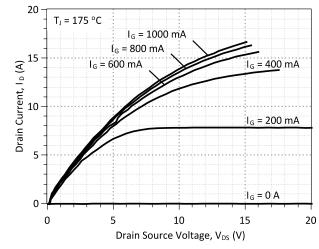
Parameter	Symbol	Symbol Conditions		Values		Unit	
Parameter	Symbol	Conditions	min.	typ.	max.	Unit	
Switching Characteristics							
Turn On Delay Time	t _{d(on)}			35		ns	
Rise Time	t _r	$V_{DD} = 1100 \text{ V}, \text{ I}_{D} = 8 \text{ A},$		37		ns	
Turn Off Delay Time	$t_{d(off)}$	$R_{G(on)} = R_{G(off)} = 44 \Omega,$ V _{GS} = -8/15 V, L = 1.1 mH,		45		ns	
Fall Time	t _f	FWD = GB05SLT12.		38		ns	
Turn-On Energy Per Pulse	Eon	T _j = 25 °C		678		μJ	
Turn-Off Energy Per Pulse	E _{off}	Refer to Figure 11 for gate current		24		μJ	
Total Switching Energy	E _{ts}	waveform		702		μJ	
Turn On Delay Time	t _{d(on)}	$\label{eq:VDD} \begin{array}{l} V_{DD} = 1100 \ V, \ I_D = 8 \ A, \\ R_{G(on)} = R_{G(off)} = 44 \ \Omega, \\ V_{GS} = -8/15 \ V, \ L = 1.1 \ mH, \\ FWD = GB05SLT12, \\ T_j = 175 \ ^{\circ}C \\ Refer to \ Figure \ 11 \ for \ gate \ current \\ waveform \end{array}$		28			
Rise Time	tr			25		ns	
Turn Off Delay Time	t _{d(off)}			44		ns	
Fall Time	t _f			33		ns	
Turn-On Energy Per Pulse	Eon			495		μJ	
Turn-Off Energy Per Pulse	E _{off}			26		μJ	
Total Switching Energy	E _{ts}	wavelolili		521		μJ	

Thermal resistance, junction - case	R _{thJC}	1.03	°C/W



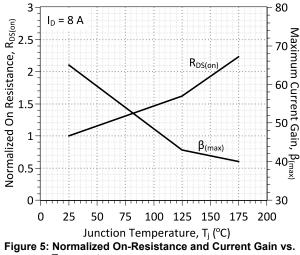




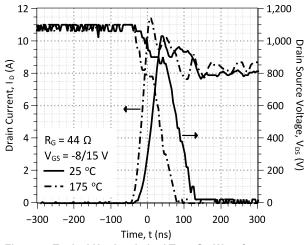


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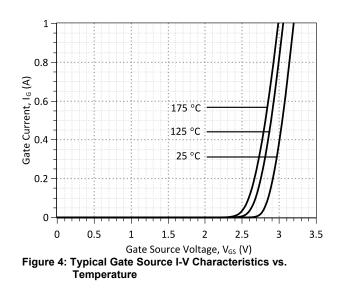
Figure 3: Typical Output Characteristics at 175 °C

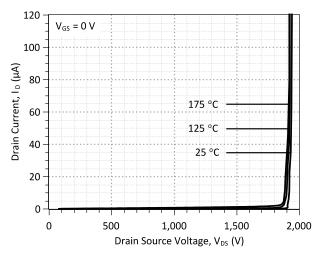


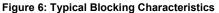
Temperature

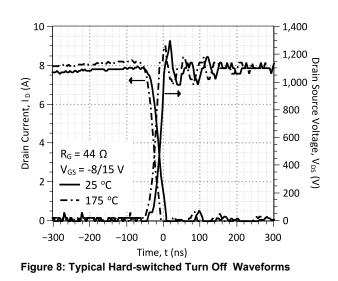






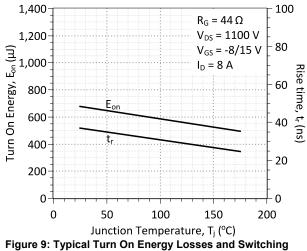


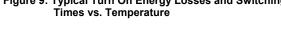




GeneSiC SEMICONDUCTOR

GA08JT17-247





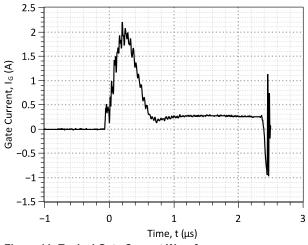
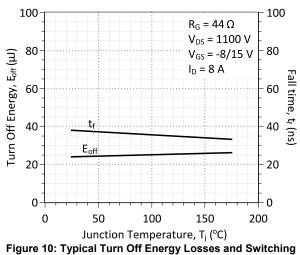


Figure 11: Typical Gate Current Waveform



Times vs. Temperature



Gate Drive Technique (Option #1)

To drive the GA08JT17-247 with the lowest gate drive losses, a custom-designed, dual voltage source gate drive configuration is recommended [for example, see Figure 5(a) in J. Rabkowski et al. IEEE Trans. Power Electronics 27(5), 2633-2642 (2012)]. More details on using this optimized gate drive technique will be made available shortly. An effective simple alternative for ultra-fast switching of the GA08JT17-247 is available below.

Gate Drive Technique (Option #2)

The GA08JT17-247 can be effectively driven using the IXYS IXDN614 / IXDD614 non-inverting gate driver IC or a comparable product. A typical gate driver configuration along with component values using this driver is offered below. Additional information is available from the manufacturer at www.ixys.com.

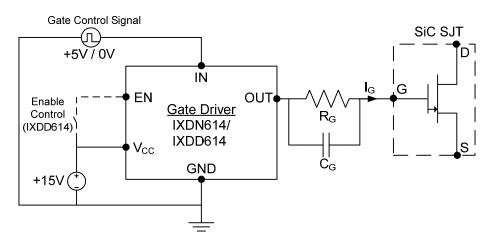
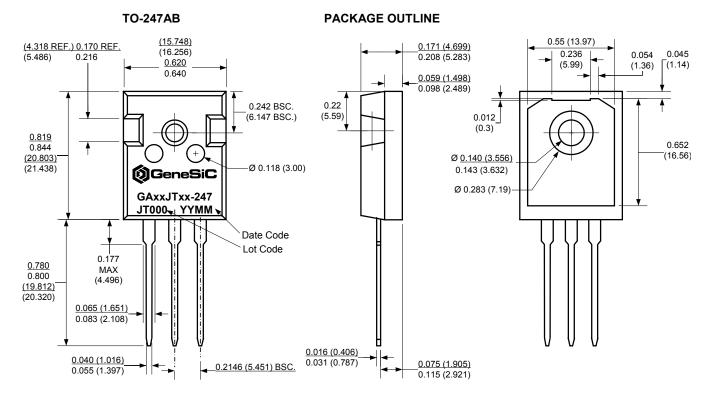


Figure 14: Recommended Gate Diver Configuration (Option #2)

Symbol Conditions	Values			11	
	Conditions	min.	typ.	max.	Unit
V _{CC}		-0.3	15	40	V
IN		-5.0	0	0.8	V
IN		3.0	5.0	V _{cc} +0.3	V
EN	IXDD614 Only			1/3*V _{CC}	V
EN	IXDD614 Only	2/3*V _{CC}			V
V _{OUT}				0.025	V
Vout		V _{CC} -0.025			V
I _{OUT}	Package Limited		4.5	14	А
I _{OUT}			0.5	4.0	А
Ι _{ουτ}			0.5	4.0	
D	1~05	5	22	1	Ω
ő	•	5			nF
	V _{сс} IN IN EN EN EN Vouт Vouт Iouт	$\begin{tabular}{c} V_{CC} \\ \hline IN \\ \hline IN \\ \hline EN & IXDD614 \ Only \\ \hline EN & IXDD614 \ Only \\ \hline V_{OUT} \\ \hline V_{OUT} \\ \hline V_{OUT} \\ \hline I_{OUT} & Package \ Limited \\ \hline I_{OUT} \\ \hline R_G & I_G \approx 0.5 \ A \end{tabular}$	V _{CC} -0.3 IN -5.0 IN 3.0 EN IXDD614 Only EN IXDD614 Only Vout 2/3*V _{CC} Vout V _{CC} -0.025 Iout Package Limited Iout IG≈0.5 A 5	$\begin{tabular}{ c c c c c } \hline Symbol & Conditions & \hline min. & typ. \\ \hline \hline \hline min. & typ. \\ \hline \hline \hline \hline \hline \hline min. & typ. \\ \hline \hline \hline \hline \hline \hline min. & typ. \\ \hline \hline \hline \hline \hline \hline \hline min. & typ. \\ \hline \hline \hline \hline \hline \hline min. & typ. \\ \hline \hline \hline \hline \hline \hline \hline min. & typ. \\ \hline \hline \hline \hline \hline \hline \hline min. & typ. \\ \hline \hline \hline \hline \hline \hline \hline min. & typ. \\ \hline \hline \hline \hline \hline \hline \hline \hline min. & typ. \\ \hline min. & typ. \\ \hline $	$\begin{tabular}{ c c c c c c c } \hline Symbol & Conditions & \hline min. & typ. & max. \\ \hline \end{tabular}$



Package Dimensions:



NOTE

1. CONTROLLED DIMENSION IS INCH. DIMENSION IN BRACKET IS MILLIMETER.

2. DIMENSIONS DO NOT INCLUDE END FLASH, MOLD FLASH, MATERIAL PROTRUSIONS

Revision History					
Date	Revision	Comments	Supersedes		
2013/02/21	1	Switching Data Added			
2012/12/03	0	Initial release			

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